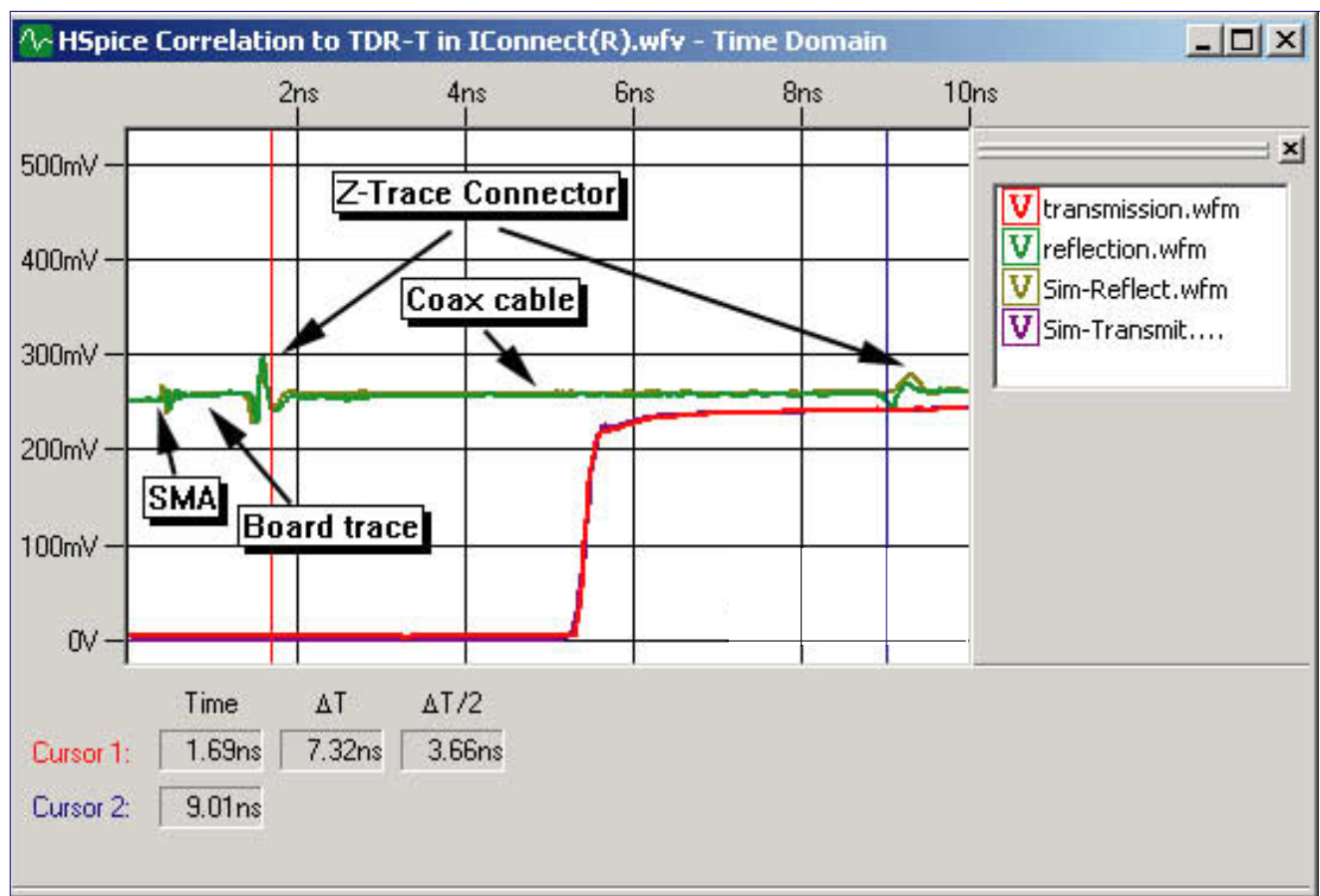


**Figure 9**



**A high level of correlation between HSpice simulation and TDR measurements allows designers to rely on the accuracy of the interconnect model.**